

ChipMOS Announces ThaiLin Entered Into A NT\$3 Billion Syndicated Loan Agreement

Hsinchu, Taiwan, February 10, 2006 - ChipMOS TECHNOLOGIES (Bermuda) LTD. ("ChipMOS" or the "Company") (Nasdaq: IMOS) announced today that ThaiLin Semiconductor Corp. ("ThaiLin"), a subsidiary 34.1% owned by the Company's 69.8% subsidiary, ChipMOS TECHNOLOGIES INC. ("ChipMOS Taiwan") has signed a syndicated loan agreement with a bank syndicate consisting of six local banks in Taiwan. ThaiLin currently expects to use the loan to expand its capacity in providing testing services for flash memory, high speed DRAM, and LCD TV peripheral IC. Mr. S.J. Cheng, Chairman and Chief Executive Officer of ChipMOS, together with Mr. Lafair Cho, President of ThaiLin, and representatives from the bank syndicate were present at the signing ceremony held in Taipei, Taiwan.

The six-year floating-rate loan provides a NT\$3 billion (approximately US\$93.8 million) credit line to ThaiLin. Among the participating banks, Hua Nan Commercial Bank, Bank of Taiwan, and China Development Industrial Bank are acting as the colead managers of the syndicate. The other three participating banks are Land Bank of Taiwan, The Farmers Bank of China, and Hsinchu International Bank.

S.J. Cheng, Chairman and Chief Executive Officer of ChipMOS, said, "The purpose of this loan facility is to fund a major portion of ThaiLin's required capital expenditure investments in 2006 as we support our existing customers, new programs scheduled to be rolled out this year and the overall expected growth in flash, DDR II memory and LCD TV peripheral IC products. I would like to express my appreciation to Hua Nan Commercial Bank, Bank of Taiwan, China Development Industrial Bank and the other three banks for their confidence in and support of ThaiLin and its management team."

About ChipMOS TECHNOLOGIES (Bermuda) LTD.:

ChipMOS (http://www.chipmos.com.tw/) is a leading independent provider of semiconductor testing and assembly services to customers in Taiwan, Japan, and the U.S. With advanced facilities in Hsinchu and Southern Taiwan Science Parks in Taiwan and Shanghai, ChipMOS and its subsidiaries provide testing and assembly services to a broad range of customers, including leading fabless semiconductor companies, integrated device manufacturers and independent semiconductor foundries.

Forward-Looking Statements

Certain statements contained in this announcement may be viewed as "forward-looking statements" within the meaning of Section 27A of the U.S. Securities Act of 1933, as amended, and Section 21E of the U.S. Securities Exchange Act of 1934, as amended. Such forward-looking statements involve known and unknown risks, uncertainties and other factors, which may cause the actual performance, financial condition or results of operations of the Company to be materially different from any future performance, financial condition or results of operations implied by such forward-looking statements. Further information regarding these risks, uncertainties and other factors is included in the Company's most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the "SEC") and in the Company's other filings with the SEC.